

SOT550-2

plastic ball grid array package; 304 balls; body 31 x 31 x 1.75 mm

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	BGA304
Package type industry code	BGA304
Package style descriptive code	BGA (ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MS-034
Mounting method type	S (surface mount)
Issue date	28-7-2004

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	30.8	-	31	31.2	mm
E	package width	30.8	-	31	31.2	mm
A	seated height	[tbd]	-	2.54	2.54	mm
A ₂	package height	1.62	-	1.75	1.84	mm
n ₂	actual quantity of termination	-	-	304	-	



2. Package outline

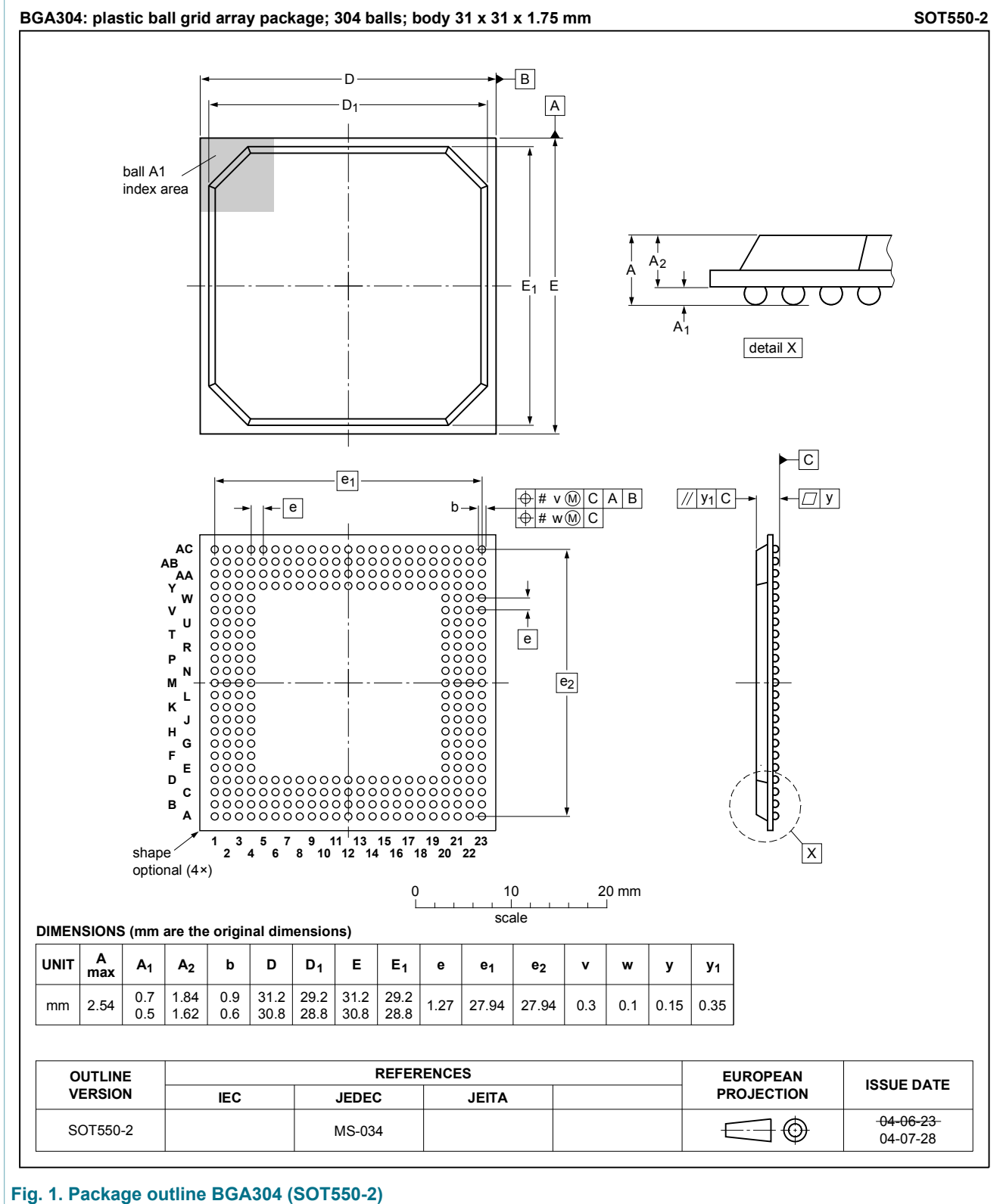


Fig. 1. Package outline BGA304 (SOT550-2)

3. Soldering

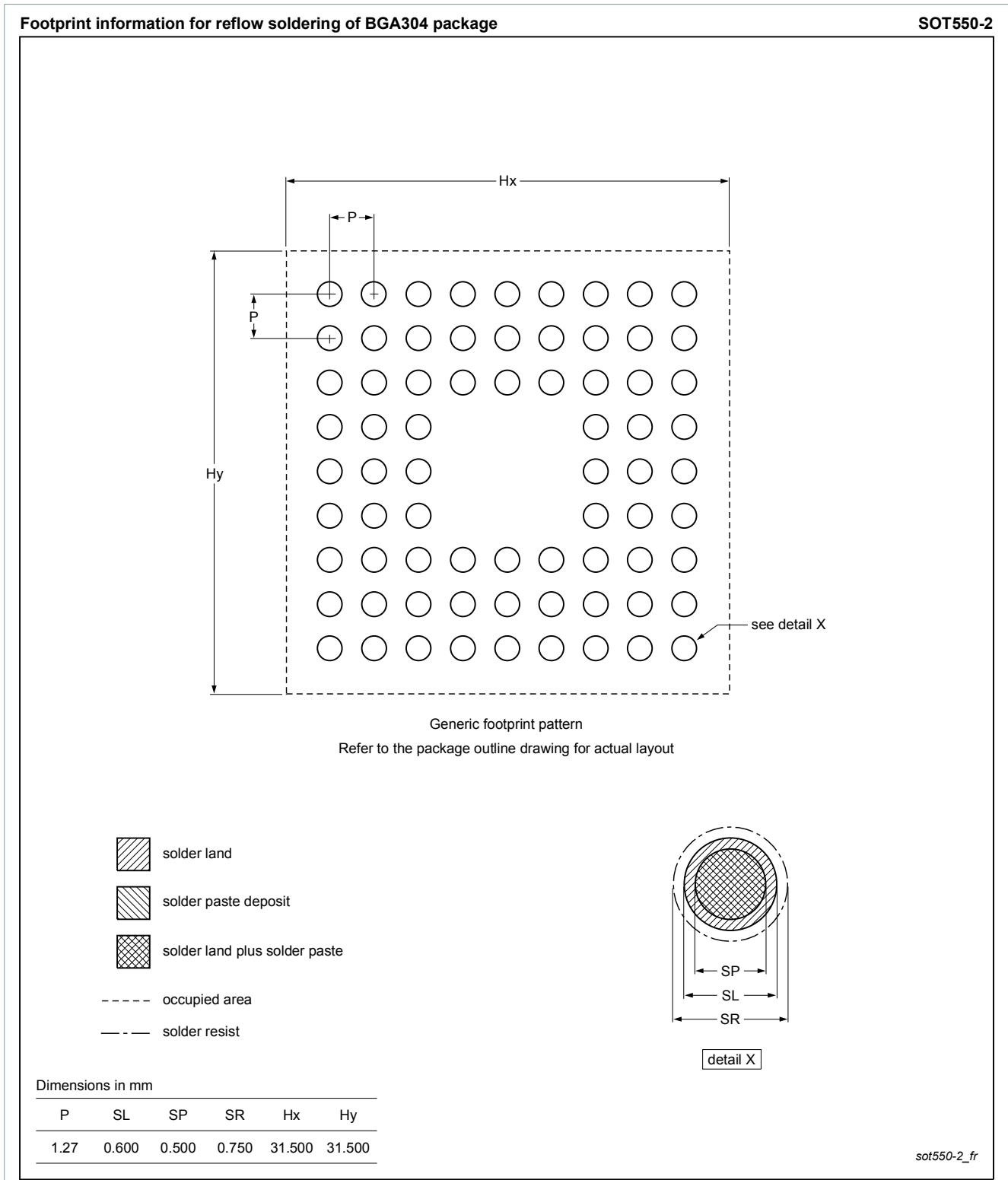


Fig. 2. Reflow soldering footprint for BGA304 (SOT550-2)

4. Legal information

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